

L Number	Hits	Search Text	DB	Time stamp
13	760	((flat near package) and (leadframe (lead adj frame)))	USPAT; EPO; JPO	2003/09/21 16:10
14	271	((flat near package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2003/09/21 16:11
15	649	((flat near package) and (leadframe (lead adj frame))) and (wire wiring)	USPAT; EPO; JPO	2003/09/21 16:11
16	7	(leadframe (lead adj frame)) near4 ((cupric adj oxide) (anodic adj oxidation) (chemical adj oxidation))	USPAT; EPO; JPO	2003/09/21 16:11
17	110	((flat near package) and (leadframe (lead adj frame)) and (wire wiring)) and ring	USPAT; EPO; JPO	2003/09/21 16:11
18	1296	((leadframe (lead adj frame)) and ((die near1 pad) (mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:12
19	282	((leadframe (lead adj frame)) and ((die near1 pad) (mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)) and (qfp qfn (quad adj flat))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:13
20	144	((leadframe (lead adj frame)) and ((die near1 pad) (mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)) and (qfp qfn (quad adj flat))) and (mold molding encapsulating encapsulated encapsulation) and (map array)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:14

L Number	Hits	Search Text	DE	Time stamp
13	760	((flat near package) and (leadframe (lead adj frame)))	USPAT; EPO; JPO	2003/09/21 16:10
14	271	((flat near package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2003/09/21 16:11
15	649	((flat near package) and (leadframe (lead adj frame))) and (wire wiring)	USPAT; EPO; JPO	2003/09/21 16:11
16	7	(leadframe (lead adj frame)) near4 ((cupric adj oxide) (anodic adj oxidation) (chemical adj oxidation))	USPAT; EPO; JPO	2003/09/21 16:11
17	110	((flat near1 package) and (leadframe (lead adj frame)))and (wire wiring)) and ring	USPAT; EPO; JPO	2003/09/21 16:11
18	1296	((leadframe (lead adj frame)) and ((die near1 pad)(mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:12
19	282	((leadframe (lead adj frame)) and ((die near1 pad)(mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)) and (qfp qfn (quad adj flat))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:13
20	144	((leadframe (lead adj frame)) and ((die near1 pad)(mounting adj (portion section area)))) and (cut cutting singulat\$3) and (method process)) and ((tooling alignment pilot sprocket feed) hole)) and (qfp qfn (quad adj flat))) and (mold molding encapsulating encapsulated encapsulation) and (map array)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/09/21 16:14
-	589	(flat near package) and (leadframe (lead adj frame))	USPAT; EPO; JPO	2003/09/21 16:10
-	201	((flat near package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2003/09/21 16:10
-	500	((flat near package) and (leadframe (lead adj frame))) and (wire wiring)	USPAT; EPO; JPO	2003/09/21 16:11
-	318	((flat near package) and (leadframe (lead adj frame))) and (wire wiring)) not ((flat near package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2001/05/20 11:07
-	5	(leadframe (lead adj frame)) near4 ((cupric adj oxide) (anodic adj oxidation) (chemical adj oxidation))	USPAT; EPO; JPO	2003/09/21 16:11
-	201	((flat near1 package) and (leadframe (lead adj frame))) and opening	USPAT; EPO; JPO	2001/05/20 11:09
-	182	((flat near1 package) and (leadframe (lead adj frame))) and opening) and (wire wiring)	USPAT; EPO; JPO	2002/10/29 15:11
-	500	(flat near1 package) and (leadframe (lead adj frame))and (wire wiring)	USPAT; EPO; JPO	2001/09/07 08:05
-	231	((flat near1 package) and (leadframe (lead adj frame))and (wire wiring)) and (plated plating)	USPAT; EPO; JPO	2001/05/20 11:12
-	522	(flat near1 package) and (leadframe (lead adj frame))and (wire wiring)	USPAT; EPO; JPO	2003/09/21 16:12
-	94	((flat near1 package) and (leadframe (lead adj frame))and (wire wiring)) and ring	USPAT; EPO; JPO	2003/09/21 16:11
-	3	((flat near1 package) and (leadframe (lead adj frame))and (wire wiring)) and ((power ground grounding) near1 ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2001/09/07 08:25
-	0	((leadframe (lead adj frame))with(tress adj reducing) with (power ground grounding))and (wire wiring)	USPAT; EPO; JPO	2001/09/07 08:50
-	5	"5776800"	USPAT; EPO; JPO	2001/09/07 08:50
-	556	(flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)	USPAT; EPO; JPO	2002/01/28 16:00
-	381	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)	USPAT; EPO; JPO	2002/01/28 16:02

-	378	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die ic (integrated adj circuit)(semiconductor near1 (device package)))	USPAT; EPO; JPO	2002/01/28 16:04
-	377	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package)))	USPAT; EPO; JPO	2002/01/28 16:16
-	364	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package))) and surface	USPAT; EPO; JPO	2002/01/28 16:16
-	115	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package))) and surface) and ((die adj pad) (mount\$3 adj (area pad)))	USPAT; EPO; JPO	2002/01/28 16:18
-	191	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package))) and surface) and (lead with (stepped step recess protrusion))	USPAT; EPO; JPO	2002/01/28 16:20
-	64	((flat near1 packag\$3) and (leadframe (lead adj frame))and (wire wiring)) and ((seal\$3 near resin) encapsulat\$3)) and (chip die (integrated adj circuit)(semiconductor near1 (device package))) and surface) and ((die adj pad) (mount\$3 adj (area pad))) and (lead with (stepped step recess protrusion))	USPAT; EPO; JPO	2002/01/28 16:20
-	12	AZUMA-KOSUKE AZUMA-KOUSUKE	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:51
-	0	20010009301.URPN.	USPAT	2002/03/27 08:51
-	9	"6071755"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	3	"6247229"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	2	"6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	14	"6071755" "6247229" "6208021"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	3	"6084310"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	3	"6163069"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52

-	6	"6198171"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:52
-	4	"6238952"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
-	4	"6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
-	19	"6084310" "6163069" "6198171" "6238952" "6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:53
-	7	("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 08:54
-	33	"6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:18
-	21	("6071755" "6247229" "6208021") (("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 09:42
-	1	6215179.URPN.	USPAT	2002/03/27 09:00
-	2	("6031292" "6215179").PN.	USPAT	2002/03/27 09:01
-	3	6031292.URPN.	USPAT	2002/03/27 09:01
-	2	("5371407" "5625222").PN.	USPAT	2002/03/27 09:02
-	0	6348726.URPN.	USPAT	2002/03/27 09:02
-	0	6208021.URPN.	USPAT	2002/03/27 09:03
-	9	("4849857" "4908736" "5444301" "5583375" "5767571" "5770888" "5801439" "5821615" "5849608").PN.	USPAT	2002/03/27 09:03
-	3	("4604644" "4974057" "5283446").PN.	USPAT	2002/03/27 09:04
-	10	5444301.URPN.	USPAT	2002/03/27 09:05
-	3	("5863805" "5886405" "5917241").PN.	USPAT	2002/03/27 09:10
-	1	6084310.URPN.	USPAT	2002/03/27 09:10
-	7	6071755.URPN.	USPAT	2002/03/27 09:11
-	10	("5285352" "5313365" "5355283" "5371404" "5394009" "5450283" "5461197" "5554887" "5578525" "5619070").PN.	USPAT	2002/03/27 09:12
-	71	5450283.URPN.	USPAT	2002/03/27 09:14
-	4	6081997.URPN.	USPAT	2002/03/27 09:19
-	9	("4143456" "4766095" "5134773" "5218759" "5420752" "5450283" "5474958" "5692296" "5732465").PN.	USPAT	2002/03/27 09:20
-	71	5450283.URPN.	USPAT	2002/03/27 09:21
-	11	("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN.	USPAT	2002/03/27 09:21
-	5	5981312.URPN.	USPAT	2002/03/27 09:25
-	5	5981312.URPN.	USPAT	2002/03/27 09:25
-	18	("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.	USPAT	2002/03/27 09:25
-	13	5817545.URPN.	USPAT	2002/03/27 09:28
-	12	("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.	USPAT	2002/03/27 09:30

-	12	((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not ((("6071755" "6247229" "6208021") ((("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:15
-	5	("5900676" "6187614" "6198171" "6201292" "6208023").PN.	USPAT	2002/03/27 09:45
-	10	("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.	USPAT	2002/03/27 09:49
-	7	5373190.URPN.	USPAT	2002/03/27 09:50
-	5	("3922712" "3959874" "3972062" "4839713" "5019673").PN.	USPAT	2002/03/27 09:53
-	84	3781596.URPN.	USPAT	2002/03/27 09:54
-	84	3781596.URPN.	USPAT	2002/03/27 09:54
-	12	5900676.URPN.	USPAT	2002/03/27 09:57
-	1	6069408.URPN.	USPAT	2002/03/27 10:02
-	7	("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.	USPAT	2002/03/27 10:02
-	13	5656550.URPN.	USPAT	2002/03/27 10:04
-	5	5830800.URPN.	USPAT	2002/03/27 10:07
-	3	("5830800" "6077766" "6232661").PN.	USPAT	2002/03/27 10:09
-	2	("5620928" "5656550").PN.	USPAT	2002/03/27 10:09
-	5	5847458.URPN.	USPAT	2002/03/27 10:10
-	5	5847458.URPN.	USPAT	2002/03/27 10:10
-	5	("4697943" "5463593" "5471088" "5497032" "5656550").PN.	USPAT	2002/03/27 10:11
-	402288	semiconductor near1 (device package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:17
-	33	(semiconductor near1 (device package packaging)) and (lead adj (pot post))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:22
-	494	(semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:25
-	216	((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:28
-	263	((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. ((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. ((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) ((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not ((("6071755" "6247229" "6208021") ((("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. ((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:30

-	211	(((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. ((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. ((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) ((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (((("6071755" "6247229" "6208021") ((("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. ((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) and (conductive adj (adhesive material epoxy)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:31
-	95	(((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. ((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. ((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) ((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (((("6071755" "6247229" "6208021") ((("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. ((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) and (conductive adj (adhesive material epoxy)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:43

-	116	<p>(((((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. ((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. ((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. ((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) not ((((((semiconductor near1 (device package packaging)) and ((leadframe (lead adj frame)) with (chip die) with (bump ball))) and ((sealing adj (resin material)) encapsulant encapsulating encapsulated)) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) 5450283.URPN. 5444301.URPN. 5450283.URPN. ((("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5371404" "5385869" "5420752" "5450283" "5623006" "5663106").PN.) 5817545.URPN. ((("5082615" "5203076" "5218234" "5244838" "5275546" "5381599" "5385869" "5450283" "5512232" "5570272" "5589714" "5609889").PN.) (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179")) not (((("6071755" "6247229" "6208021") ("6084310" "6163069" "6198171" "6238952" "6215179") and (bump ball)))) ((("3781596" "5157475" "5302849" "5309429" "5373190" "5521429" "5554887" "5581444" "5659200" "5849608").PN.) 3781596.URPN. ((("5298460" "5623123" "5656550" "5856212" "5893724" "5900676" "5930603").PN.) 5656550.URPN.)) and (conductive adj (adhesive material epoxy)))</p> <p>"116" and (lead near2 exposed)</p>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:44
-	535		USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/27 10:45